

Lite On Technology WSG300NRC Wi-Fi HaLow 802.11ah Module User Manual

Home » Lite On Technology » Lite On Technology WSG300NRC Wi-Fi HaLow 802.11ah Module User Manual

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Contents [hide

- 1 Overview
 - 1.1 Module features
 - 1.2 Applications
- 2 Block Diagram
- 3 Pin Description
- **4 Absolute Maximum Rating**
- **5 Operating Condition**
 - 5.1 Operating condition
 - 5.2 Current consumption
 - 5.3 Power on sequence
- 6 AC Specifications
 - 6.1 HSPI timing
 - **6.2 SPI Timing**
 - **6.3 AUXADC Timing**
- 7 11ah WLAN RF Specifications and

Performance

- 7.1 Transmitter Specifications
- 7.2 Receiver Specifications
- 7.3 Transmitter Performance
- 7.4 Receiver Performance
- **8 Product Characteristic**
 - **8.1 Product Dimension**
 - **8.2 PAD Dimension**
 - 8.3 Recommend footprint
- 9 SMT Temperature Sequence (Pb-free)
- 10 FCC Statement
- 11 Documents / Resources
- **12 Related Posts**

Overview

IEEE 802.11ah is a new Wi-Fi standard operating in the Sub 1GHz license-exempt band, offering longer range and lower power connectivity necessary for internet of things (IoT) applications. WSG300NRC contains external RF front end module (FEM) which can increase transmission power up to 23 dBm. Onboard serial flash can be used for OTA software development and with internal 32KB cache memory, it can support execution in place (XIP) feature.

Module features

The main features are represented as follows:

- Standard
 - IEEE Std 802.11ahTM-2016 compliant
 - 1/2/4 MHz channel bandwidth support
 - WPA2 PSK support
 - 150 kbps ~ 15 Mbps data rate
 - AP and STA role support
- · Radio frequency
 - -109 dBm minimum receive sensitivity
 - +23 dBm transmit power
 - 920.5~924.5 MHz frequency band (By replacing RF SAW filter, other frequency band can be supported within 750~950 MHz)
- CPU
 - ARM Cortex-M3 for application
 - ARM Cortex-M0 for IEEE 802.11ah WLAN
 - Clock frequencies for both processor (32/48 MHz)
- · Host interface
 - UART and SPI support for host interface
- Peripherals
 - GPIO, ADC, PWM and timers
 - I2C, SPI and UART
- · Temperature range
 - -40°C to +125°C

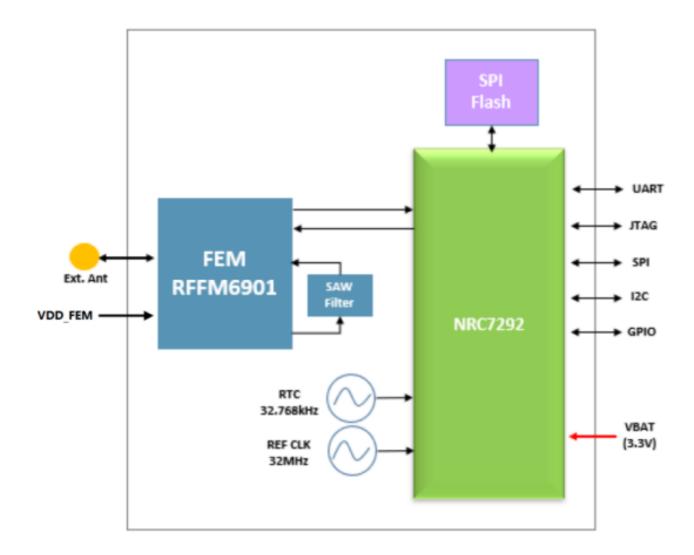
Applications

Low to high data rate can be applied in various IoT applications like:

- Wearable
- Home automation
- Healthcare
- · Industrial automation
- Safety and security
- · Smart grid

Multimedia streaming

Block Diagram



Pin Description

65	63 63 64	800	55 55	68
3 4 5	GND		GND	51 50 40 48
7 8				45
9 10 11 12 12	GND		GND	44 43 42 41
13				29
15 16 17 18 19	GND		GND	37 37 36 35 34
20	R	27	R R H	23 67

Part no.	Name	Direction	Volt	Description
1	GROUND	GND		
2	GROUND	GND		
3	GROUND	GNO		
4	GROUND	GND		
5	VDD FEM	Р		Module power input for FEM

6	VBAT_33V	Р	Module power input for SYS
7	GROUND	GND	
8	GROUND	GND	
9	MODE 00	I	SW define (When ROM BOOT) 11: Internal SRAM BOO
10	MODE 01	I	T
11	MODE 02	I	0: ROM BOOT 1:)0P BOOT
12	MODE 03	I	0: Cortex-MO Mater 1: Cortex-M3 Mater
13	MODE 04	I	0: Two CPU 1: One CPU
14	GROUND	GND	
15	HSPI_nCS	I	Host SPI-Chip Select (active low)
16	HSPI_CUC	I	Host SPI-Clock
17	HSPI MISO	0	Host SPI-Mater in Slave out
18	HSPI_MOSI	I	Host SPI-Mater out Slave in
19	HSPI_EIRQ	0	Host SPI-Interrupt
20	GROUND	GND	

21	GROUND	GND	
22	NC	_	
23	NC	_	
24	NC	_	
25	GP 00 UART2 TX	I/O	UART Channel2 Tx
26	GP 01 UART2_RX	I/O	UART Channel2 Rx
27	GP 02 UART2_RTS	I/O	UNIT Channel2 RTS
28	GP 03_UART2 CTS	I/O	UART Channel2 CTS
29	GP 04 UARTO TX	I/O	UNIT Channel0 Tx
30	GP 05_UARTO_RX	I/O	UNIT Channel0 Rx
31	GP 06 UART3 TX	I/O	UART Channel3 Tx
32	GP 07 UART3_RX	I/O	UNIT Channel3 Rx
33	GP 08 UARTI_FIX	I/O	UART Channell Rx
34	GP_11 UART1 TX	I/O	UART Channell Tx
35	GP10 GPIO	I/O	Multiple purpose (GPIO, I2C, PWM, SPI, Ext-INT)

36	GP 09 GPIO	I/O	
37	GP_17 I2C SDA	I/O	I2C SDA
38	GP 16 I2C SCL	I/O	I2C SCL
39	GP_15_SSPO_CUC	0	SPIO Clock
40	PD_14_SSPO_CS	0	SPIO Chip Enable (active low)
41	PD_13_SSPO_MOSI	0	SPIO_Mater out Slave in
42	PD_12_SSPO_MISO	1	SPIO_Mater in Slave out
43	RESET	1	Reset (active high)
44	GROUND	GND	
45	JTAG TRSTN	1	JTAG reset
46	HAG TMS	I	JTAG mode selection
47	HAG Ta	I	JTAG dock
48	JTAG TDI	0	JTAG data input
49	JTAG TDO	1	JTAG data output
50	GROUND	GND	

51	VDDIO	Р	Module I/0 supply input
52	GROUND	GND	
53	GROUND	GND	
54	AUXADCIN3	I	AUXADC input 3
55	AUXADCIN2	I	AUXADC input 2
56	AUXADCIN1	I	AUXADC input 1
57	GROUND	GND	
58	NC	-	
59	NC	-	
60	GROUND	GND	
61	GROUND	GND	
62	RF ANT	I/O	RF IN/OUT
63	GROUND	GND	
64	GROUND	GND	
65	GROUND	GND	

66	GROUND	GND	
67	GROUND	GND	
68	GROUND	GND	

Absolute Maximum Rating

Symbol Rating		Min	Max	1:nits
Storage Temperature	-40	+125	°C	
Supply Voltage	VBAT	-0.5	3.8	V
Supply voltage	VDDIO	-0.5	3.8	V

NOTE: Stresses above those listed in Absolute Maximum Rating may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Operating Condition

Operating condition

Symbol	Rating	Min	Тур	Max	1:nits
Operating Temperature Range		-40	_	+85	°C
Operating Voltage	VBAT	2.8	3.3	3.6	V
Operating voitage	VDDIO	1.8	3.3	VBAT	V

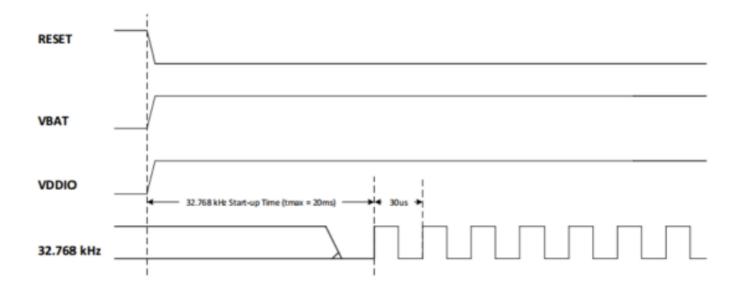
NOTE: To ensure WLAN performance, ripple on the 2.1- to 3.3-V supply must be less than ± 300 mV and ripple on the 1.8-V supply must be less than 2% (± 40 mV).

Current consumption

Mode	i _ i i —)t.: llm L-	Band (MHz)	VBAT=3.3V, Ta=27°C		
802.11ah (1Mhz BW)	TX@18dBm	9)2	200		
OUZ. I TAIT (TIVITIZ DVV)	Continuous RX@-80dBm	3)2	41		
802.11ah (2Mhz BW)	TX@18dBm	922	290		
OUZ. I TAIT (ZIVIIIZ DVV)	Continuous RX@-80dBm	922	41		
802.11ah (4Mhz BW)	TX@18dBm	922	200		
	Continuous RX@-80dBm	JEE	42		

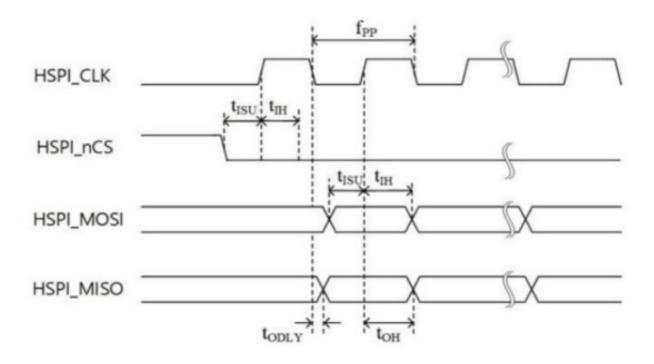
Note: Unless otherwise specified, TA=27°C, VBAT=3.6V, using internal PMU. Measurements are done at antenna port, which is directly connect to the device.

Power on sequence



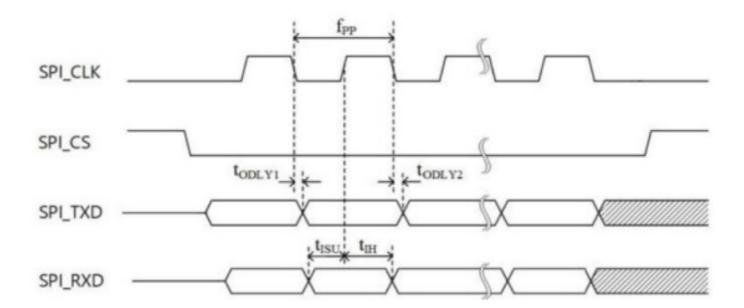
AC Specifications

HSPI timing



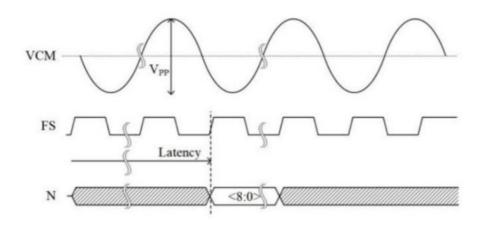
Symbol	Parameter	Min	Тур	I Max	Unit
fpp	Frequency	_	_	25	MHz
tom	Output delay time	6	_	_	ns
to,,	Output hold time	2	_	_	ns
tisu	Input setup time	_	_	14	ns
Us	Input hold time	3.	_	_	ns

SPI Timing



Symbol		Parameter		Mi n	Тур	Max	Unit
fnn	Frequency		mast er	_	24	24	MH z
fpp Frequency			slave	_	_	4	MH z
tort	Output delay time I			0	_	10	MH z
tOD1Y2	Output delay time 2			0	_	10	ns
tsu	Input setup time			18	_	_	ns
tu,	Input hold time			20	_	_	ns

AUXADC Timing



		I				
Symbol	Parameter	Min	Тур	Max	Unit	
VCM	Input common-mode voltage		0.28	0.31	V	
Vpp	Input Swing	_	0.5	_	Vpp	
FS	Sampling Clock	_	32	_	MHz	
Latency	Conversion latency(1 cycle = 31.25 ns)	_	11	_	cycle	
N	Resolution	_	9	_	Bit	
RIN	Input impedance	_	1	_	Mohms	
(_active	Current consumption (1.2V supply)	_	_	300	uA	
!down	Power-down current (1.2V supply)	_	_	1	uA	

11ah WLAN RF Specifications and Performance

Transmitter Specifications

Parameter	Conditions	Min	Тур	Max	Unit
RF Output Freq uency Range in		920.5		924.5	MHz
EVM compliant Output Power	13.5 Mbps (MC S7, 4 MHz BW)			18	dBm
EVM at 0 dBm o utput power				33	dB
Transmitter	<700 MHz			<-36	dBm/
Spurious Signal i Emissions	>1GHz			<45	MHz
RF Output Retur n Loss	Single ended ou tput port			-10	dB
Output 1dB Gai n Compression	0.4 MHz CW sig nal input			25	dBm
Gain Control Ra		30	30		dB
Gain Control St ep				1	dB
Unwanted Sideb and	Over RF channe I, RF frequency, and baseband fr equency at 0 dB m output power			<-40	dBc

Note: Unless otherwise specified, TA=27°C, VBAT=3.6V, RF input/output specifications are referenced not device pins and do not include 1dB loss from EV kit OCB and SMA connector.

(1) RF output frequency range depends on RF SAW filter on the module. The NRC7292 chipset by itself can support frequency range from 750 to 950 MHz.

Receiver Specifications

1 Parameter	Conditions	Min	Тур	Max	Unit	
RF Input Frequency Range "I		921.		925.	MHz	
RF Input Return Loss	For LNA high/mid/low gain modes	-10	-12	-15	dB	
' Total Voltage Gain Range	Analog + Digital Gain	-10		92	dB	
RF Gain Step	From high gain mode to medium gain mo de		6		dB	
RX Gain Step	From RF to Analog		1		dB	
DSB Noise Figure	LNA max gain mode		4.		dB	
IIP3	LNA with high gain mode		-17		dBm	
	LNA with low gain mode		24		dBm	

Baseband Filters for Receiver (log + Digital Filter)							
Baseband -3dB Low-pass Corner Frequency (Controllable)	1 MHz channel		0.5		MHz		
	2 MHz channel		1.0		MHz		
	4 MHz channel		2.0		MHz		

Note: Unless otherwise specified, TA=27°C, VBAT=3.6V, RF input/output specifications are referenced not device pins and do not include 1dB loss from EV kit OCB and SMA connector. (1) RF output frequency range depends on RF SAW filter on the module. The NRC7292 chipset by itself can support frequency range from 750 to 950 MHz.

Transmitter Performance

DR/MCS/BW bPs//MHz (hA)	LEE Relative constellation error (dB)	EVM (%) (IEEE)	WM (%) (NRM7292A)	Comments
0.15/MCS10/1	-4	63.	3.	BPSK Peak
0.30/MCS0/1	-5	56.	3.	BPSK Peak

0.60/MCS1/1	-10	32.	3.	18 dBm OFDM, RMS
0.90/MCS2/1	-13	22.	3.	18 dBm OFDM, RMS
1.20/MCS3/1	-16	16.	3.	18 dBm OFDM, RMS
1.80/MCS4/1	-19	11.	3.	18 dBm OFDM, RMS
2.40/MCS5/1	-22	8.	3.	18 dBm OFDM, RMS
2.70/MCS6/1	-25	6.	3.	18 dBm OFDM, RMS
3.00/MCS7/1	-27	5.	3.	18 dBm OFDM, RMS
0.65/MCS0/2	-5	56.	3.	BPSK Peak
1.30/MCS1/2	-10	32.	3.	18 dBm OFDM, RMS
1.95/MCS2/2	-13	22.	3.	18 dBm OFDM, RMS
2.60/MCS3/2	-16	16.	3.	18 dBm OFDM, RMS
3.90/MCS4/2	-19	11.	3.	18 dBm OFDM, RMS
5.20/MCS5/2	-22	8.	3.	18 dBm OFDM, RMS
5.85/MCS6/2	-25	6.	3.	18 dBm OFDM, RMS
6.50/MCS7/2	-27	5.	3.	18 dBm OFDM, RMS
1.35/MCS0/4	-5	56.	3.0	BPSK Peak
2.70/MCS1/4	-10	32.	3.0	18 dBm OFDM, RMS
4.05/MCS2/4	-13	22.	3.0	18 dBm OFDM, RMS
5.40/MCS3/4	-16	16.	3.0	18 dBm OFDM, RMS
8.10/MCS4/4	-19	11.	3.0	18 dBm OFDM, RMS
10.80/MCS5/4	-22	8.	3.0	18 dBm OFDM, RMS

12.15/MCS6/4	-25	6.	3.0	18 dBm OFDM, RMS
13.50/MCS7/4	-27	5.	3.0	_ 18 dBm OFDM, RMS

Note: <Conditions> supply voltage VBAT 2.6-3.6V, TA=25°C, Signal within spectrum mask.

Receiver Performance

Receiver Sensitivity

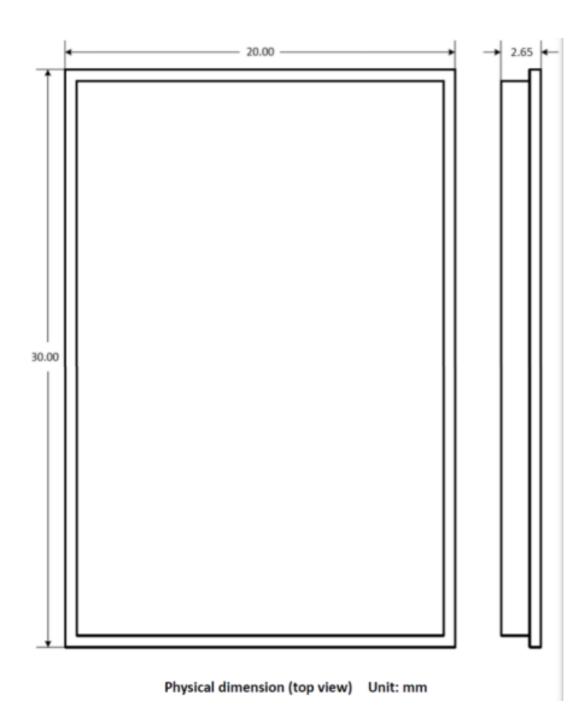
Band	BW	Rate	Modulation/Coding Rate	Conditions/Conditions	Chip Po	[dBm]	fication
		kbps			Min	Тур	Max
		300	BPSK 1/2			-105	
		600	QPSK 1/2			-103	
- 1		900	QPSK 3/4	@ PER<10%, 256 bytes		-100	
- 1		1200	16QAM 1/2	Full Operating		-97	
- 1	1 MHz	1800	16QAM 3/4	Temperature; Full Battery Voltage		-94	
- 1		2400	64QAM 2/3	Range;		-90	
- 1			Load Z:50 Ohms;		-88		
- 1		3000	64QAM 5/6			-87	
		150	BPSK 1/2 rep. 2x			-108	
		650	BPSK 1/2	@ PER<10%, 256 bytes Full Operating Temperature; Full Battery Voltage Range; Load Z:50 Ohms;		-101	
- 1		1300	QPSK 1/2			-98	
920.5~		1950	QPSK 3/4			-95	
924.5M	2 MHz	2600	16QAM 1/2			-92	
Hz	2 IVIHZ	3900	16QAM 3/4			-89	
- 1		5200	64QAM 2/3			-85	
- 1		5850	64QAM 3/4			-83	
- 1		6500	64QAM 5/6			-82	
- 1		1350	BPSK 1/2			-98	
- 1		2700	QPSK 1/2	@ DED-10W 356 hates		-95	
I		4050	QPSK 3/4	@ PER<10%, 256 bytes Full Operating		-92	
	4 MHz	5400 160AM 1/2 Temperature:	The state of the s		-89		
I	4 MHZ	8100	16QAM 3/4	Full Battery Voltage		-86	
I		10800 64QAM 2/3 Range;			-82		
		12150	64QAM 3/4 Load Z : 50 Ohms;	Load Z : 50 Ohms;		-80	
- 1		13500	64QAM 5/6			-79	

Adjacent Channel Rejection (ACR)

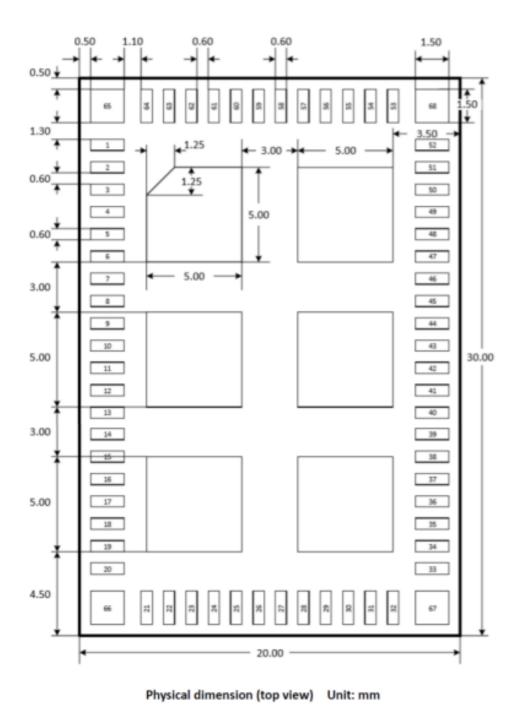
Band	BW	Rate	Modulation/Coding Rate	Conditions/Conditions		ACR [dB	1
		kbps			Min	Тур	Max
		300	BPSK 1/2			32	
		600	QPSK 1/2	1		30	
		900	QPSK 3/4			29	
- 1		1200	16QAM 1/2	@ PER<10%,		28	
- 1	1 MHz	1800	16QAM 3/4	P _{desired} =P _{sensitivity} + 3dB,		25	
- 1		2400	64QAM 2/3	P _{interfere}]@ N+1 channel		24	
- 1		2700	64QAM 3/4			23	
- 1		3000	64QAM 5/6	1 [22	
- 1	-	150	BPSK 1/2 rep. 2x			35	
- 1		650	BPSK 1/2			30	
		1300	QPSK 1/2	1		28	
920.5~		1950	QPSK 3/4			27	
924.5M	2 MHz	2600	16QAM 1/2	@ PER<10%, Pdesired=Psensitivity + 3dB, Pinterfere]@ N+1 channel		26	
Hz	ZIVITZ	3900	16QAM 3/4			23	
- 1		5200	64QAM 2/3			21	
- 1		5850	64QAM 3/4			19	
		6500	64QAM 5/6	1		17	
I		1350	BPSK 1/2			28	
		2700	QPSK 1/2			26	
		4050	QPSK 3/4			25	
		5400	16QAM 1/2	@ PER<10%,		23	
	4 MHZ	4 MHz 8100	16QAM 3/4	P _{desired} =P _{sensitivity} + 3dB, P _{interfere}]@ N+1 channel		20	
		10800	64QAM 2/3			18	
		12150	64QAM 3/4	1		15	
		13500	64QAM 5/6	1		12	

Product Characteristic

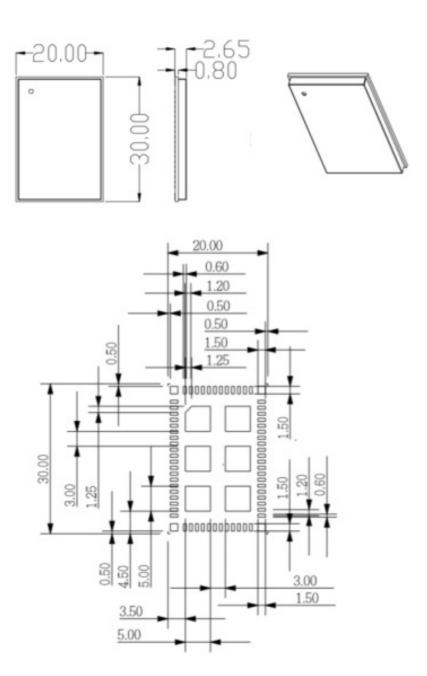
Product Dimension



PAD Dimension

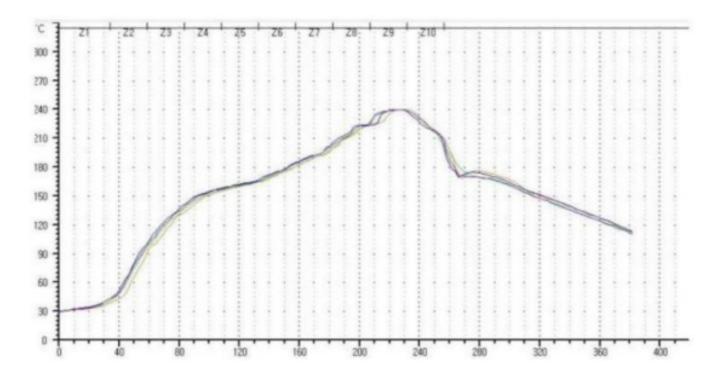


Recommend footprint



SMT Temperature Sequence (Pb-free)

Reflow profile



FCC Statement

Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. For product available in the USA/Canada market, only channel 1~11 can be operated. Selection of other channels is not possible. This device and its antenna(s) must not be colocated with any other transmitters except in accordance with FCC multi transmitter product procedures. Referring to the multi transmitter policy, multiple transmitter(s) and module(s) can be operated simultaneously without C2PC.

IMPORTANT NOTE: FCC Radiation Exposure Statement: This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator & your body.

IMPORTANT NOTE: This module is intended for OEM integrator. The OEM integrator is responsible for the

compliance to all the rules that apply to the product into which this certified RF module is integrated. Additional testing and certification may be necessary when multiple modules are used.

20 cm minimum distance has to be able to be maintained between the antenna and the users for the host this module is integrated into. Under such configuration, the FCC radiation exposure limits set forth for an population/uncontrolled environment can be satisfied. Any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment.

USERS MANUAL OF THE END PRODUCT:

In the user's manual of the end product, the end user has to be informed to keep at least 20 cm separation with the antenna while this end product is installed and operated. The end user has to be informed that the FCC radio frequency exposure guidelines for an uncontrolled environment can be satisfied. The end user has to also be informed that any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment. If the size of the end product is smaller than 8x10cm, then additional FCC part 15.19 statement is required to be available in the user's manual: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

LABEL OF THE END PRODUCT:

The final end product must be labeled in a visible area with the following "Contains FCC ID: PPQ-WSG300NRC". If the size of the end product is larger than 8x10cm, then the following FCC part 15.19 statement has to also be available on the label: This device complies with Part 15 of FCC rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference and (2) this device must accept any interference received, including interference that may cause undesired operation.

OEM Integrator Checklist

The party below will implement the LITE-ON Module in host systems in accordance with the instructions specified in this document and the documents referenced herein.

- 1. The OEM integrator will ensure the Module is integrated in a host systems using only the approved antenna model(s) described in this document.
- 2. The OEM integrator will ensure the antenna placement inside the host system will maintain the required spacing to end user for RF Exposure compliance, as specified in this document.
- 3. If other radios are integrated inside the host with the LITE-ON Module, the OEM integrator will contact its test lab, TCB or LITE-ON to determine if additional FCC compliance evaluation is required to meet FCC collocation rules.
- 4. The OEM integrator will ensure end user documentation will contain the specified regulatory wording and ensure the host system and the Module itself are labeled as specified in this document.
- 5. The OEM integrator will ensure the Module is programmed in the factory with compliant transmit power not exceeding the levels specified in this document. LITE-ON requests that the OEM integrator acknowledge its receipt of this document and the above instructions. You may contact LITE-ON with any questions concerning this document or the responsibilities of the OEM integrator

Documents / Resources



<u>Lite On Technology WSG300NRC Wi-Fi HaLow 802.11ah Module</u> [pdf] User Manual WSG300NRC, PPQ-WSG300NRC, PPQWSG300NRC, WSG300NRC Wi-Fi HaLow 802.11ah Module, Wi-Fi HaLow 802.11ah Module

Manuals+, home privacy